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HXMSH2GS03A2F1C-16K

204-Pin Small Outline DDR3 SDRAM Modules
EU RoHS Compliant

Data Sheet

Rev. B

Revision History:		
Date	Revision	Subjects (major changes since last revision)
2013/08/01	A	Initial Release
2016/03/01	B	Change to UnilC Format

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Table of Contents

1	Overview	3
1.1	Features	3
1.2	Description	4
2	Pin Configurations.....	5
2.1	Pin Configurations.....	5
3	General Description.....	9
3.1	General Description.....	9
3.2	Serial Presence-Detect EEPROM Operation.....	9
4	Electrical Characteristics	10
4.1	Absolute Maximum Ratings.....	10
4.2	Operating Conditions.....	11
4.3	Module and Component Speed Grades	12
4.4	AC Timing Requirements.....	13
4.5	IDD Specifications and Conditions	14
5	Package Dimensions.....	17

1 Overview

This chapter gives an overview of the 204-pin Small Outline DDR3 SDRAM modules product family and describes its main characteristics.

1.1 Features

- 204-Pin PC3-12800 Small Outline DDR3 SDRAM memory modules.
- Single rank 256M x 64 module organization, by 8pcs 256M x 8 chips organization.
- 2GB Modules built with 2Gbit DDR3 SDRAMs in chipsize package FBGA-78 ball.
- Standard Double-Data-Rate-Three Synchronous DRAMs (DDR3 SDRAM) with a single + 1.5 V (± 0.075 V) power supply.
- All speed grades faster than DDR3-1600 complies with DDR3-1600 timing specifications.
- Programmable CAS Latencies (6, 8, 9,10,11), Burst Length 8 (BL8),Burst Chop 4 (BC4) .
- Auto Refresh (CBR) and Self Refresh.
- Auto Refresh for temperatures above 85 °C $t_{REFI} = 3.9 \mu\text{s}$.
- Programmable self refresh rate via MR2 setting.
- Programmable partial array refresh via MR2 settings.
- All inputs and outputs SSTL_1.5 compatible.
- Off-Chip Driver Impedance Adjustment (OCD) and On-Die Termination (ODT).
- Serial Presence Detect with E²PROM.
- Small Outline DIMM Dimensions (nominal): 30 mm high, 67.6 mm wide
- Based on standard reference layouts.

TABLE 1
Module Performance Table

UniIC Speed Code		-16K	Unit	Note
DRAM Speed Grade	DDR3	-1600		
Module Speed Grade	PC3	-12800		
CAS-RCD-RP latencies		11-11-11	t_{CK}	
Max. Clock Frequency	CL8	f_{CK8}	533	MHz
	CL9	f_{CK9}	667	MHz
	CL10	f_{CK10}	667	MHz
	CL11	f_{CK11}	800	MHz
Min. RAS-CAS-Delay	t_{RCD}	13.75	ns	
Min. Row Precharge Time	t_{RP}	13.75	ns	
Min. Row Active Time	t_{RAS}	35	ns	
Min. Row Cycle Time	t_{RC}	48.75	ns	

1.2 Description

The UniIC HXMSH2GS03A2F1C-16K module family are Small Outline DIMM modules with 30 mm height based on DDR3 technology. DIMMs are available in 256M × 64 (2GB) in organization and density, intended for mounting into 204-pin connector sockets.

The memory array is designed with 2 Gbit Double-Data-Rate-Three (DDR3) Synchronous DRAMs. Decoupling capacitors are mounted on the PCB board. The DIMMs feature serial presence detect based on a serial E²PROM device using the 2-pin I²C protocol. The first 128 bytes are programmed with configuration data and are write-protected; the second 128 bytes are available to the customer.



TABLE 2
Ordering Information

Product Type ¹⁾	Compliance Code ²⁾	Description	SDRAM Technology
PC3-12800 (11-11-11)			
HXMSH2GS03A2F1C-16K	2GB 1R×8 PC3-12800-11-11-11	1 Rank	2Gbit (×8)

1) For detailed information regarding Product Type of UniIC please see chapter "Product Type Nomenclature" of this data sheet.

2) The Compliance Code is printed on the module label and describes the speed grade, for example "PC3-12800-11-11-11" where 12800 means DIMM modules with 12.80 GB/sec Module Bandwidth and "11-11-11" means Column Address Strobe (CAS) latency=11, Row Column Delay (RCD) latency = 11 and Row Precharge (RP) latency = 11.

TABLE 3
Address Format

DIMM Density	Module Organization	Memory Ranks	ECC/ Non-ECC	# of SDRAMs	# of row/bank/column bits
2GB	256M × 64	1	Non	8	15/3/10

TABLE 4
Components on Modules

DRAM Components ¹⁾²⁾	DRAM Density	DRAM Organization
HXB15H2G800BF-13K	2Gbit	256M × 8

1) Green Product

2) For a detailed description of all functionalities of the DRAM components on these modules see the component data sheet.

2 Pin Configurations

2.1 Pin Configurations

The pin configuration of the 204-Pin Small Outline DDR3 SDRAM DIMM is listed by function in [Table 5](#) (204 pins). The abbreviations used in columns Pin Type and Buffer Type are explained in [Table 6](#) and [Table 7](#) respectively. The Pin numbering is depicted in [Figure 1](#)

TABLE 5
Pin Configuration of SO-DIMM

Symbol	Type	Description
Ax	Input	Address inputs: Provide the row address for ACTIVE commands, and the column address and auto precharge bit (A10) for READ/WRITE commands, to select one location out of the memory array in the respective bank. A10 sampled during a PRECHARGE command determines whether the PRECHARGE applies to one bank (A10 LOW, bank selected by BAx) or all banks (A10 HIGH). The address inputs also provide the op-code during a LOAD MODE command. See the Pin Assignments Table for density-specific addressing information.
BAx	Input	Bank address inputs: Define the device bank to which an ACTIVE, READ, WRITE, or PRECHARGE command is being applied. BA define which mode register (MR0, MR1, MR2, or MR3) is loaded during the LOAD MODE command.
CKx, CKx#	Input	Clock: Differential clock inputs. All control, command, and address input signals are sampled on the crossing of the positive edge of CK and the negative edge of CK#.
CKEx	Input	Clock enable: Enables (registered HIGH) and disables (registered LOW) internal circuitry and clocks on the DRAM.
DMx	Input	Data mask (x8 devices only): DM is an input mask signal for write data. Input data is masked when DM is sampled HIGH, along with that input data, during a write access. Although DM pins are input-only, DM loading is designed to match that of the DQ and DQS pins.
ODTx	Input	On-die termination: Enables (registered HIGH) and disables (registered LOW) termination resistance internal to the DDR3 SDRAM. When enabled in normal operation, ODT is only applied to the following pins: DQ, DQS, DQS#, DM, and CB. The ODT input will be ignored if disabled via the LOAD MODE command.
Par_In	Input	Parity input: Parity bit for Ax, RAS#, CAS#, and WE#.
RAS#, CAS#, WE#	Input	Command inputs: RAS#, CAS#, and WE# (along with S#) define the command being entered.
RESET#	Input (LVCMOS)	Reset: RESET# is an active LOW asynchronous input that is connected to each DRAM and the registering clock driver. After RESET# goes HIGH, the DRAM must be reinitialized as though a normal power-up was executed.
Sx#	Input	Chip select: Enables (registered LOW) and disables (registered HIGH) the command decoder.
SAx	Input	Serial address inputs: Used to configure the temperature sensor/SPD EEPROM address range on the I ² C bus.

SCL	Input	Serial clock for temperature sensor/SPD EEPROM: Used to synchronize communication to and from the temperature sensor/SPD EEPROM on the I ² C bus.
CBx	I/O	Check bits: Used for system error detection and correction.
DQx	I/O	Data input/output: Bidirectional data bus.
DQSx, DQSx#	I/O	Data strobe: Differential data strobes. Output with read data; edge-aligned with read data; input with write data; center-aligned with write data.

Symbol	Type	Description
SDA	I/O	Serial data: Used to transfer addresses and data into and out of the temperature sensor/SPD EEPROM on the I ² C bus.
TDQSx, TDQSx#	Output	Redundant data strobe (x8 devices only): TDQS is enabled/disabled via the LOAD MODE command to the extended mode register (EMR). When TDQS is enabled, DM is disabled and TDQS and TDQS# provide termination resistance; otherwise, TDQS# are no function.
Err_Out#	Output (open drain)	Parity error output: Parity error found on the command and address bus.
EVENT#	Output (open drain)	Temperature event: The EVENT# pin is asserted by the temperature sensor when critical temperature thresholds have been exceeded.
V _{DD}	Supply	Power supply: 1.5V ±0.075V. The component V _{DD} and V _{DDQ} are connected to the module V _{DD} .
V _{DDSPD}	Supply	Temperature sensor/SPD EEPROM power supply: 3.0–3.6V.
V _{REFCA}	Supply	Reference voltage: Control, command, and address V _{DD} /2.
V _{REFDQ}	Supply	Reference voltage: DQ, DM V _{DD} /2.
V _{SS}	Supply	Ground.
V _{TT}	Supply	Termination voltage: Used for control, command, and address V _{DD} /2.
NC	–	No connect: These pins are not connected on the module.
NF	–	No function: These pins are connected within the module, but provide no functionality.

TABLE 6
Abbreviations for pin Type

Abbreviation	Description
I	Standard input-only pin. Digital levels.
O	Output. Digital levels.
I/O	I/O is a bidirectional input/output signal.
AI	Input. Analog levels.
PWR	Power
GND	Ground
NC	Not Connected

TABLE 7
Abbreviations for Buffer Type

Abbreviation	Description
SSTL	Serial Stub Terminated Logic (SSTL_15)
LV-CMOS	Low Voltage CMOS
CMOS	CMOS Levels
OD	Open Drain. The corresponding pin has 2 operational states, active low and tri-state, and allows multiple devices to share as a wire-OR.

FIGURE 1
Pin Configuration SO-DIMM (204 pin)

Pin	Signal	Pin	Signal	Pin	Signal	Pin	Signal	Pin	Signal	Pin	Signal
1	VREFDQ	41	DQ17	81	VDD	121	/S1	161	VSS	201	SA1
2	VSS	42	DQ21	82	VDD	122	NC	162	VSS	202	SCL
3	VSS	43	VSS	83	A12	123	VDD	163	DQ48	203	VTT
4	DQ4	44	VSS	84	A11	124	VDD	164	DQ52	204	VTT
5	DQ0	45	/DQS2	85	A9	125	TEST	165	DQ49		
6	DQ5	46	DM2	86	A7	126	VREFCA	166	DQ53		
7	DQ1	47	DQS2	87	VDD	127	VSS	167	VSS		
8	VSS	48	VSS	88	VDD	128	VSS	168	VSS		
9	VSS	49	VSS	89	A8	129	DQ32	169	/DQS6		
10	/DQS0	50	DQ22	90	A6	130	DQ36	170	DM6		
11	DM0	51	DQ18	91	A5	131	DQ33	171	DQS6		
12	DQS0	52	DQ23	92	A4	132	DQ37	172	VSS		
13	VSS	53	DQ19	93	VDD	133	VSS	173	VSS		
14	VSS	54	VSS	94	VDD	134	VSS	174	DQ54		
15	DQ2	55	VSS	95	A3	135	/DQS4	175	DQ50		
16	DQ6	56	DQ28	96	A2	136	DM4	176	DQ55		
17	DQ3	57	DQ24	97	A1	137	DQS4	177	DQ51		
18	DQ7	58	DQ29	98	A0	138	VSS	178	VSS		
19	VSS	59	DQ25	99	VDD	139	VSS	179	VSS		
20	VSS	60	VSS	100	VDD	140	DQ38	180	DQ60		
21	DQ8	61	VSS	101	CK0	141	DQ34	181	DQ56		
22	DQ12	62	/DQS3	102	CK1	142	DQ39	182	DQ61		
23	DQ9	63	DM3	103	/CK0	143	DQ35	183	DQ57		
24	DQ13	64	DQS3	104	/CK1	144	VSS	184	VSS		
25	VSS	65	VSS	105	VDD	145	VSS	185	VSS		
26	VSS	66	VSS	106	VDD	146	DQ44	186	/DQS7		
27	/DQS1	67	DQ26	107	A10/AP	147	DQ40	187	DM7		
28	DM1	68	DQ30	108	BA1	148	DQ45	188	DQS7		
29	DQS1	69	DQ27	109	BA0	149	DQ41	189	VSS		
30	/RESET	70	DQ31	110	/RAS	150	VSS	190	VSS		
31	VSS	71	VSS	111	VDD	151	VSS	191	DQ58		
32	VSS	72	VSS	112	VDD	152	/DQS5	192	DQ62		
33	DQ10	73	CKE0	113	/WE	153	DM5	193	DQ59		
34	DQ14	74	CKE1	114	/S0	154	DQS5	194	DQ63		
35	DQ11	75	VDD	115	/CAS	155	VSS	195	VSS		
36	DQ15	76	VDD	116	ODT0	156	VSS	196	VSS		
37	VSS	77	NC	117	VDD	157	DQ42	197	SA0		
38	VSS	78	A15	118	VDD	158	DQ46	198	NC		
39	DQ16	79	BA2	119	A13	159	DQ43	199	VDDSPD		
40	DQ20	80	A14	120	ODT1	160	DQ47	200	SDA		

3 General Description

3.1 General Description

DDR3 SDRAM modules are high-speed, CMOS dynamic random access memory modules that use internally configured 4 or 8-bank DDR3 SDRAM devices. DDR3 SDRAM modules use DDR architecture to achieve high-speed operation. DDR3 architecture is essentially a $8n$ -prefetch architecture with an interface designed to transfer two data words per clock cycle at the I/O pins. A single read or write access for the DDR3 SDRAM module effectively consists of a single $8n$ -bit-wide, one-clock-cycle data transfer at the internal DRAM core and eight corresponding n -bit-wide, one-half-clock-cycle data transfers at the I/O pins.

DDR3 modules use two sets of differential signals: DQS, DQS# to capture data and CK and CK# to capture commands, addresses, and control signals. Differential clocks and data strobes ensure exceptional noise immunity for these signals and provide precise crossing points to capture input signals. A bidirectional data strobe (DQS, DQS#) is transmitted externally, along with data, for use in data capture at the receiver. DQS is a strobe transmitted by the DDR3 SDRAM device during READs and by the memory controller during WRITEs. DQS is edge-aligned with data for READs and center-aligned with data for WRITEs.

DDR3 SDRAM modules operate from a differential clock (CK and CK#); the crossing of CK going HIGH and CK# going LOW will be referred to as the positive edge of CK. Commands (address and control signals) are registered at every positive edge of CK. Input data is registered on both edges of DQS, and output data is referenced to both edges of DQS, as well as to both edges of CK.

3.2 Serial Presence-Detect EEPROM Operation

DDR3 SDRAM modules incorporate serial presence-detect. The SPD data is stored in a 256-byte EEPROM. The first 128 bytes are programmed by UniIC to identify the module type and various SDRAM organizations and timing parameters. The remaining 128 bytes of storage are available for use by the customer. System READ/WRITE operations between the master (system logic) and the slave EEPROM device occur via a standard I2C bus using the DIMM's SCL (clock) SDA (data), and SA (address) pins. Write protect (WP) is connected to VSS, permanently disabling hardware write protection.

4 Electrical Characteristics

This chapter contains speed grade definition, AC timing parameter and ODT tables.

4.1 Absolute Maximum Ratings

Attention: Stresses greater than those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

TABLE 8
Absolute Maximum Ratings

Symbol	Parameter	Rating		Unit	Note
		Min.	Max.		
V_{DD}	Voltage on V_{DD} pin relative to V_{SS}	-0.4	+1.975	V	
V_{DDQ}	Voltage on V_{DDQ} pin relative to V_{SS}	-0.4	+1.975	V	
V_{IN}, V_{OUT}	Voltage on any pin relative to V_{SS}	-0.4	+1.975	V	

Attention: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to integrated circuit.

TABLE 9
Module Environmental Requirements

Parameter	Symbol	Values		Unit	Note
		Min.	Max.		
Operating temperature (ambient)	T_{OPR}	0	+65	°C	
Storage Temperature	T_{STG}	- 50	+100	°C	
Barometric Pressure (operating & storage)	PBar	+69	+105	kPa	1)

1) Up to 3000m.

TABLE 10

DRAM Component Operating Temperature Range

Symbol	Parameter	Rating		Unit	Note
		Min.	Max.		
T_{CASE}	Operating Temperature	0	95	°C	1)2)3)4)

- 1) Operating Temperature is the case surface temperature on the center / top side of the DRAM.
- 2) The operating temperature ranges are the temperatures where all DRAM specification will be supported. During operation, the DRAM case temperature must be maintained between 0 - 95 °C under all other specification parameters.
- 3) Above 85 °C the Auto-Refresh command interval has to be reduced to $t_{REFI} = 3.9 \mu s$
- 4) When operating this product in the 85 °C to 95 °C T_{CASE} temperature range, the High Temperature Self Refresh has to be enabled by setting EMR(2) bit A7 to "1". When the High Temperature Self Refresh is enabled there is an increase of I_{DD6} by approximately 50%

4.2 Operating Conditions

TABLE 11

Supply Voltage Levels and AC / DC Operating Conditions

Parameter	Symbol	Values			Unit	Note
		Min.	Typ.	Max.		
Device Supply Voltage	V_{DD}	1.425	1.5	1.575	V	
Output Supply Voltage	V_{DDQ}	1.425	1.5	1.575	V	1)
Input Reference Voltage	V_{REF}	$0.49 \times V_{DDQ}$	$0.5 \times V_{DDQ}$	$0.51 \times V_{DDQ}$	V	2)
SPD Supply Voltage	V_{DDSPD}	3	—	3.6	V	
DC Input Logic High	$V_{IH(DC)}$	$V_{REF} + 0.1$	—	V_{DDQ}	V	
DC Input Logic Low	$V_{IL(DC)}$	vss	—	$V_{REF} - 0.1$	V	
AC Input Logic High	$V_{IH(AC)}$	$V_{REF} + 0.175$	—		V	
AC Input Logic Low	$V_{IL(AC)}$		—	$V_{REF} - 0.175$	V	
In / Output Leakage Current	I_L	- 5	—	5	μA	3)

- 1) Under all conditions, V_{DDQ} must be less than or equal to V_{DD}
- 2) Peak to peak AC noise on V_{REF} may not exceed $\pm 2\% V_{REF}$ (DC). V_{REF} is also expected to track noise in V_{DDQ} .
- 3) Input voltage for any connector pin under test of $0 V \leq V_{IN} \leq V_{DDQ} + 0.3 V$; all other pins at 0 V. Current is per pin

4.3 Module and Component Speed Grades

DDR3 components may exceed the listed module speed grades; module may not be available in all listed speed grades

TABLE 12	
Module and Component Speed Grades	
Module Speed Grade	Component Speed Grade
-16K	1600MHz

4.4 AC Timing Requirements

This chapter describes the AC timing requirements.

TABLE 13
AC Timing Requirements

Symbol	AC Characteristics Parameter	Min	Max	Unit
tCK(DLL_OFF)	Minimum Clock Cycle Time (DLL off mode)	8	-	ns
tCH(avg)	Average high pulse width	0.47	0.53	tCK(avg)
tCL(avg)	Average low pulse width	0.47	0.53	tCK(avg)
tDQSQ	DQS, DQS# to DQ skew, per group, per access	-	100	ps
tQH	DQ output hold time from DQS, DQS#	0.38	-	tCK(avg)
tDS(base)	Data setup time to DQS, DQS# referenced to Vih(ac) / Vil(ac) levels	10	-	ps
tDH(base)	Data hold time from DQS, DQS# referenced to Vih(dc) / Vil(dc) levels	45	-	ps
tDIPW	DQ and DM Input pulse width for each input	360	-	ps
tRPRE	DQS, DQS# differential READ Preamble	0.9	-	tCK(avg)
tRPST	DQS, DQS# differential READ Postamble	0.3	-	tCK(avg)
tQSH	DQS, DQS# differential output high time	0.40	-	tCK(avg)
tQSL	DQS, DQS# differential output low time	0.40	-	tCK(avg)
tWPRE	DQS, DQS# differential WRITE Preamble	0.9	-	tCK(avg)
tWPST	DQS, DQS# differential WRITE Postamble	0.3	-	tCK(avg)
tDQSCK	DQS, DQS# rising edge output access time from rising CK, CK#	-255	255	ps
tLZ	DQ, DQS and DQS# low-impedance time	-450	250	ps
tHZ	DQ, DQS and DQS# high-impedance time	-	250	ps
tDQSL	DQS, DQS# differential input low pulse width	0.45	0.55	tCK(avg)
tDQSH	DQS, DQS# differential input high pulse width	0.45	0.55	tCK(avg)
tDQSS	DQS, DQS# rising edge to CK, CK# rising edge	-0.27	0.27	tCK(avg)
tDSS	DQS, DQS# falling edge setup time to CK, CK# rising edge	0.18	-	tCK(avg)
tDSH	DQS, DQS# falling edge hold time from CK, CK# rising edge	0.18	-	tCK(avg)
tRTP	Internal READ Command to PRECHARGE Command delay	max(4nCK, 7.5ns)	-	-
tWTR	Delay from start of internal write transaction to internal read command	max(4nCK, 7.5ns)	-	-
tWR	WRITE recovery time	15	-	ns
tMRD	Mode Register Set command cycle time	4	-	nCK
tIS(base)	Command and Address setup time to CK, CK# referenced to Vih(ac) / Vil(ac) levels	45	-	ps
tIH(base)	Command and Address hold time from CK, CK# referenced to Vih(dc) / Vil(dc) levels	120	-	ps
tXP	Exit Power Down with DLL on to any valid command; Exit Precharge Power Down with DLL frozen to commands not requiring a locked DLL	max(3nCK, 6ns)	-	-
tCKE	CKE minimum pulse width	max(3nCK, 5.625ns)	-	-
tREFI	Average Periodic Refresh interval	85°C < TCASE < 95°C / 3.9	0°C < TCASE < 85°C / 7.8	us

4.5 I_{DD} Specifications and Conditions

List of tables defining I_{DD} Specifications and Conditions.

TABLE 14		
I_{DD} Measurement Conditions		
Parameter	Symbol	Note¹⁾²⁾ 3)4)5)
Operating Current 0 One bank Active - Precharge; $t_{CK} = t_{CK.MIN}$; $t_{RC} = t_{RC.MIN}$; $t_{RAS} = t_{RAS.MIN}$; \overline{CS} is HIGH, \overline{CS} is HIGH between valid commands. Address and control inputs are SWITCHING, Databus inputs are SWITCHING.	I_{DD0}	
Operating Current 1 One bank Active - Read - Precharge; $I_{OUT} = 0$ mA, $\overline{BL} = 4$, $t_{CK} = t_{CK.MIN}$; $t_{RC} = t_{RC.MIN}$; $t_{RAS} = t_{RAS.MIN}$; $t_{RCD} = t_{RCD.MIN}$; $AL = 0$, $CL = CL_{MIN}$; \overline{CS} is HIGH, CS is HIGH between valid commands. Address and control inputs are SWITCHING, Databus inputs are SWITCHING.	I_{DD1}	6)
Operating Current - Burst Read All banks open; Continuous burst reads; $BL = 4$; $AL = 0$, $CL = CL_{MIN}$; $t_{CK} = t_{CKMIN}$; $t_{RAS} = t_{RASMAX}$; $t_{RP} = t_{RPMIN}$; \overline{CS} is HIGH, CS is HIGH between valid commands; Address inputs are SWITCHING; Data bus inputs are SWITCHING; $I_{OUT} = 0$ mA.	I_{DD4R}	6)
Operating Current - Burst Write All banks open; Continuous burst writes; $BL = 4$; $AL = 0$, $CL = CL_{MIN}$; $t_{CK} = t_{CK.MIN}$; $t_{RAS} = t_{RAS.MAX}$; $t_{RP} = t_{RP.MAX}$; \overline{CS} is HIGH, CS is HIGH between valid commands. Address inputs are SWITCHING; Data Bus inputs are SWITCHING;	I_{DD4W}	
Burst Refresh Current $t_{CK} = t_{CK.MIN}$; Refresh command every $t_{RFC} = t_{RFC.MIN}$ interval, \overline{CS} is HIGH, CS is HIGH between valid commands, Other control and address inputs are SWITCHING, Data bus inputs are SWITCHING.	I_{DD5B}	
Self-Refresh Current $\overline{CS} \leq 0.2$ V; external clock off, CK and CK at 0 V; Other control and address inputs are FLOATING, Data bus inputs are FLOATING. I_{DD6} current values are guaranteed up to T_{CASE} of 85 °C max.	I_{DD6}	
All Bank Interleave Read Current All banks are being interleaved at minimum t_{RC} without violating t_{RRD} using a burst length of 4. Control and address bus inputs are STABLE during DESELECTS. $I_{out} = 0$ mA.	I_{DD7}	6)

- 1) $V_{DDQ} = 1.5 \text{ V} \pm 0.1 \text{ V}$; $V_{DD} = 1.5 \text{ V} \pm 0.1 \text{ V}$
- 2) I_{DD} specifications are tested after the device is properly initialized and I_{DD} parameter are specified with ODT disabled.
- 3) Definitions for I_{DD} see [Table 16](#)
- 4) For two rank modules: All active current measurements in the same I_{DD} current mode. The other rank is in I_{DD2P} Precharge Power-Down Mode.
- 5) For details and notes see the relevant UnilC component data sheet.
- 6) I_{DD1} , I_{DD4R} and I_{DD7} current measurements are defined with the outputs disabled ($I_{OUT} = 0$ mA). To achieve this on module level the output buffers can be disabled using an EMRS(1) (Extended Mode Register Command) by setting A12 bit to HIGH.

TABLE 15
Definitions for I_{DD}

Parameter	Description
LOW	$V_{IN} \leq V_{IL(ac).MAX}$, HIGH is defined as $V_{IN} \geq V_{IH(ac).MIN}$
STABLE	Inputs are stable at a HIGH or LOW level.
FLOATING	Inputs are $V_{REF} = V_{DDQ} / 2$
SWITCHING	Inputs are changing between HIGH and LOW every other clock (once per 2 cycles) for address and control signals, and inputs changing between HIGH and LOW every other data transfer (once per cycle) for DQ signals not including mask or strobes.

TABLE 16
 IDD Specification for HXMSH2GS03A2F1C-16K

Product Type	HXMSH2GS03A2F1C-16K	Unit	Note ¹⁾²⁾
Organization	2 GB		
	1 Rank (×8)		
	×64		
	-16K		
Symbol	Max.		
I_{DD0}	560	mA	3)
I_{DD1}	760	mA	3)
I_{DD2N}	280	mA	4)
I_{DD2P0}	96	mA	4)
I_{DD2Q}	280	mA	4)
I_{DD3N}	360	mA	4)
I_{DD3P}	280	mA	4)
I_{DD4R}	1280	mA	3)
I_{DD4W}	1280	mA	3)
I_{DD5B}	1160	mA	3)
I_{DD6}	96	mA	4)
I_{DD7}	1920	mA	3)

1) Calculated values from component data. ODT disabled. I_{DD1} , I_{DD4R} and I_{DD7} are defined with the outputs disabled.

2) $I_{DDX (rank)} = \text{Number of components} \times I_{DDX (component)}$

3) $I_{DDX} = I_{DDX (rank)} + (\text{Rank}-1) \times I_{DD2P (rank)}$

4) $I_{DDX} = \text{Rank} \times I_{DDX (rank)}$

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